

GE Aviation Systems July 23rd, 2010



Market Sector:

Aerospace & Defense Manufacturing of Composite Structure Components

Current Customers:

- *Air Force Research Laboratory (AFRL)
- * Missile Defense Agency (MDA)
- * Robinsons Helicopter
- * GE Aviation Systems (GEAS)
- * BAE Systems
- * ITT

- * US Air Force ManTech
- * US Navy
- * National Composite Center (NCC)
- * Tracewell Systems
- * Lockheed Martin
- * Quickstep Composites, LLC

Financial Projections:

Sales: \$1.5M in 2010; and \$10M in 2015 EBITDA: \$0.07M in 2010; and \$1.6M in 2015

• Facilities:

Vector Composites, Inc - Dayton, OH

- 30,000 Sq ft full service manufacturing, and research and development facility.
- Certified ISO9001:2008 and AS9100 Registered (Lloyds Register)



Vector's Mission:

Vector Composites is committed to become a leader in the research, development and manufacture of composite structural aerospace parts and sub-assemblies for both military and commercial applications.

The Vector team is dedicated to providing innovative, high technology, high quality, low cost composite solutions that both meet and exceed customer demands.

Vector Composites is committed to utilize its state-of- the-art 30,000 square foot facility in a way that provides safe, flexible manufacturing capabilities that utilizes Lean manufacturing concepts to provide the best overall value for the customer.



Our History

December, 18th 2003

Established / National Composite Center: October, 2003

Kettering, OH

Developing VARTM and P4A Technologies

5000 Sq/Ft Facility

July, 10th 2006

Acquired by DR Technologies, Inc (San Diego, CA)

Kettering, OH

May 28th, 2008

Relocated to the Advanced Materials Technology Center

Dayton, Ohio

- 30,000 Sq/Ft Facility

June 4th, 2010

Acquired by Composite Technology Investors, LLC

Vector Composites, Inc. – Wholly Owned Subsidiary

Dayton, OH

The Ohio Advantage

- Located within Ohio "Aerospace HUB" Technology Corridor
- HUB Zone, Small Business



Advanced Materials Research & Development

Composite Prototyping

Materials Development

- Carbon Nano Fibers
- Carbon Nano Fillers
- Nano Adhesives
- Thermally Conductive Materials

Manufacturing Services

- Quickstep Out of Autoclave Processing
- Ply Cutting, Kitting & Fabrication Services
- Resin Transfer Molding (RTM)
- Composite Fabrication
- Room Temperature, Autoclave, Oven, Press Cures
- Composite Machining

Design Capability

- Conceptual, Preliminary Thru Final Product Design
- CATIA V5 w/ & SolidWorks CPD

Analysis Capability

- Structural
- Thermal
- Acoustic
- Electrical
- Impact





Facility - Manufacturing & Development Workspace







Facility Accommodates Large
 Open Floor Plan
 Hardware & Large Tooling

Large Aisles







Safety Program

Maintenance Cage

Secure MRB Control Area



Facility - Manufacturing & Development Workspace







Quality Lab



Large Loading Docks (2)



Employee Break Room



Leased Expansion Space



• Leased Expansion Space



Facility - Manufacturing & Development Equipment





- 4' x 6' Capacity, 600F



50 Ton Platen Press

- Size: 45"x24"x22", Temp 550F



Job Shop

- Milling, Drilling, Cutting, Grinding



Large Clean Room

- Size: 2,500 Sq Ft, Class 100K Vector Composites, Inc. - Proprietary



NC Router

- 5 Axis, Vacuum Table



Ply Cutter

- NC Controlled, Table = 5' x 20'



Facility - Manufacturing & Development Equipment





- Size: 6'x4'x3', Temp: 550F



Paint / Mixing Booth

- Size: 14'x 18'x 9'



Medium Oven

- Size: 10'x 8'x 12', Temp: 550F



Large Walk In Freezer

- Size: 9'x 7'x 7' Temp: -10F Vector Composites, Inc. - Proprietary



Large Oven

- Size: 8'x 8' x 30' Temp 550F



RTM System

- Size: 2.5 Gal





Teammates & Project Roles

Applied Sciences, Inc.

Supplier of CNFs, Milled, Unmilled, and Functionalized

NanoSperse, LLC

Supplier of Formulated Dispersed Resins

Renegade Materials Supplier of Resins to NanoSperse for Disbursement and Fabricator of Films and Nanopreg

University of Dayton Research Institute

Nano-Particle Recommendations and Testing of Multi-Functional Properties

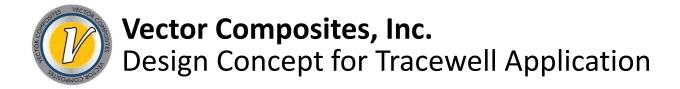
GE Aviation Systems

User Provider of electronic enclosure design i.e. cost, weight, producibility & operational needs



- UDRI leading multi-faceted program for Ohio technology development
- Several companies tasked to develop technology using protective coatings
- Vector addressing EMI protection for composites via coatings
- Vector Tasks
 - Design requirements and coatings development
 - Nano-material structural development
 - Nano-material composite electronic enclosure demonstration
 - Market development for electronic enclosure products

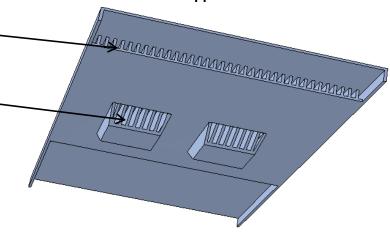
Vector is working with Dayton RCP team to develop materials and manufacturing technology in a way that promotes our regional supply chain & manufacturing strategy.



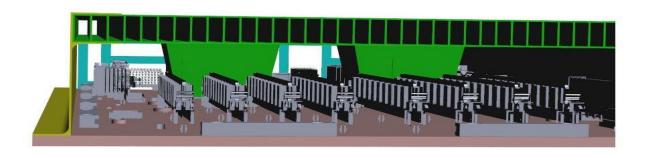
Full composite concept includes:

- Highly conductive materials
- Upper sandwich with cooling fins
- Cup integrates composite finned heat sink to maximize convective cooling
- Base plate → Stiffness





Cut-Away of Full Assembly (Design Option)





Envelope (max abs)

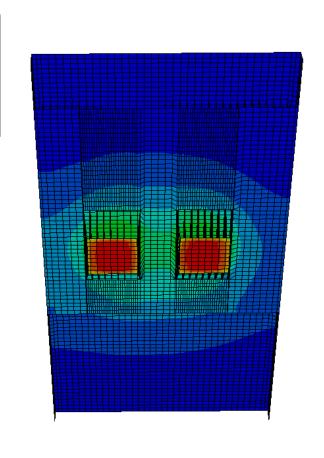
(Avg: 75%)

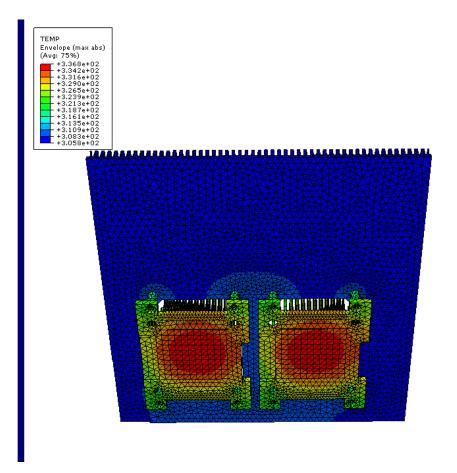
Vector Composites, Inc.

Thermal Modeling for Tracewell Application

Max temp: 342.9° K (69.75° C)

Max temp: 336.8° K (63.65° C)





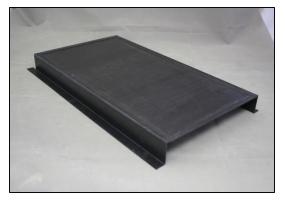
Co-eff of heat transfer: 25 W/m ²K















Project Title: Nano-Composite Structures Manufacturing Technology Development

Project Objective:

Develop and demonstrate affordable composite structures manufacturing technology for application to multifunctional integrated electronic and structure components for aerospace and defense system applications.

Project Scope:

- MFG processes development using nano-materials and lower cost composite structures mfg processes
- Characterization testing of composite structures to used in developing a design database
- Fabrication of full-scale structures to demonstrate mfg processes
- Include system users to insert technology into production

Project Task Elements:

- # 1) MFG development of multi-functional nano composite structures using low cost composite mfg processes.
- # 2) Characterization of multi-functional nano-composite structures using low cost composite mfg processes.
- # 3) Development of nano-composite structures technology for use in aircraft electronics packaging applications.

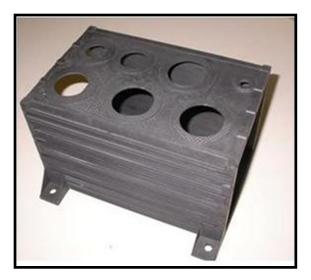
Project Schedule: 18 Months

Fiscal Year Funding: GFY09-\$800,000 Appropriated

\$635,000 Vector contract awarded to UDRI, from AFRL with Vector as a subcontractor



Insertion application identified on F-35 platform







- Experience with manufacturing of electronics enclosures, including above enclosure with application requirements from F-35 application
- Leveraging intellectual property, mfg tooling, mfg processing technologies, and production systems to aid nano-technology development



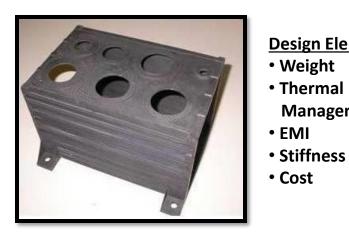
Development Program Deliverables – Electronic Enclosures



Multi-Functional Composite Electronic Enclosures - Missile and Aircraft

10 Msi modulus

\$250-\$500/lb



Design Element

 Weight
 Thermal

 Management

 TO W/m²
 EMI

 Advanced Composites

 45% reduction

 160-300 W/m² with high conductivity fibers
 >60 dB; (aluminum plating baseline)

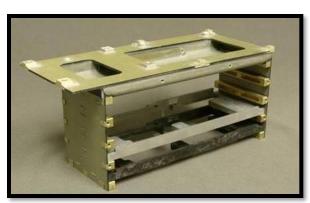
8-15 Msi modulus

\$500-1,500/lb



Design Notes

- Thinnest laminate construction
- Eliminated stiffeners
- 46% weight reduction vs. aluminum
- Meets all structural/mechanical requirements
- Meets EMI requirements via aluminum plating



Design Notes

- 35% weight reduction vs. beryllium baseline
- Co-cured aluminum mesh for ESD
- Co-cured fasteners for assembly and system integration



Vector Gamposites In Composite Electronic Enclosures Military Aircraft Composite Chassis



Molded Composite Details

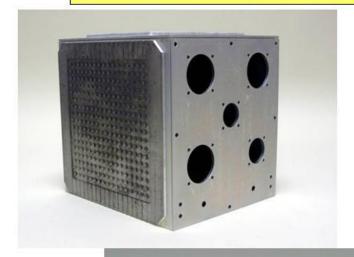
- Improved Producibility Bladder & Compression Molding
- · Utilized Hi-E Gr fibers to reduce wt
 - Thinnest laminate
 - · Eliminated stiffeners
- Wt reduction vs alum
 - 63% (bare)/ 60%(plated) Chassis w/o coldwall
 - · 61%(bare)/56%(plated) Front Plt
 - 62%(bare)/56%(plated) –Top Cover
 - 30% (plated) w/ alum Coldwall
 - 40%(plated) w/ composite Coldwall
- Meets all Structural/Mechanical Regm'ts
- Meets EE Reqm'ts via alum plating

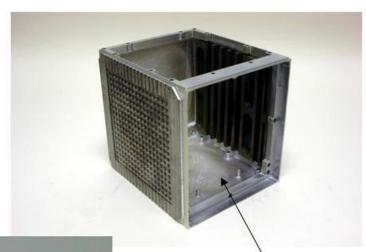




Aircraft Electronic Enclosure- Assembly & Cold-Wall

Assembled Composite Chassis with Carbon-Carbon Coldwall



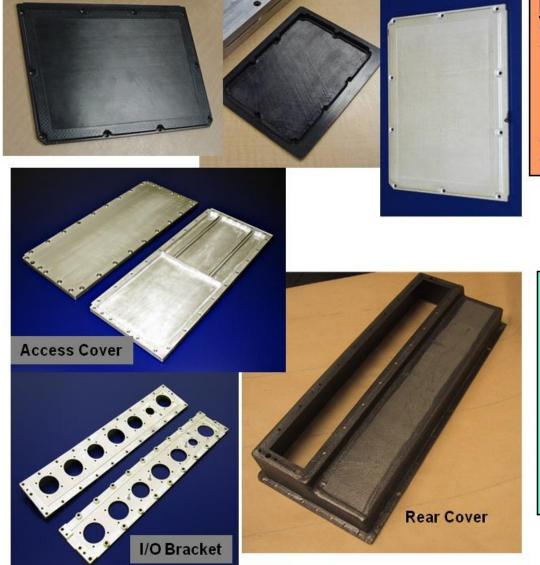




Plated Structural Chassis with post-bonded C-C Chassis (Niplated)



Vector Composites, Inc.Aircraft Composite Module & Rack Covers



Module Cover

- Improved Producibility Compression Molding
- Utilized Hi-E Gr fibers to reduce wt
 - Thinnest laminate
 - · Eliminated stiffeners
 - · 65% (bare)/56% (plated) Wt reduction vs alum
 - 30% Lighter than chopped fiber technology
- · Meets all Structural/ Mechanical Regm'ts
- · Meets EE Reqm'ts via alum plating

Rack Covers

- Improved Producibility Bladder & Compression Molding
- · Utilized Hi-E Gr fibers to reduce wt
 - Thinnest laminate
 - · Eliminated stiffeners
 - Wt reduction vs alum
 - 58% (bare)/ 46%(plated) Access Cover
 - 47%(bare)/37%(plated) I/O Bracket
 - · 46%(bare)/40%(plated) Rear Cover
- · Meets all Structural/Mechanical Regm'ts
- Meets EE Reqm'ts via alum plating



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